Ref #	Hits	Search Query	DBs	Default Operator	Pluraļs	Time Stamp
	2	"20020023765"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 08:06
L4	21	(US-20020023765-\$).did. or (US-6031231-\$ or US-6316770-\$ or US-6891259-\$ or US-6238085-\$ or US-7022990-\$ or US-6686653-\$ or US-6603183-\$ or US-5369280-\$ or US-7038288-\$ or US-5689087-\$ or US-6222111-\$ or US-6163061-\$ or US-5374123-\$ or US-6949286-\$ or US-6229144-\$ or US-5804847-\$ or US-6627518-\$ or US-6335478-\$).did. or (US-6384473-\$ or US-6603183-\$). did.	US-PGPUB; USPAT; DERWENT	OR	ON	2006/05/10 08:21
L5	1	L4 and monocrysta\$6 and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:14
L6	1	L4 and monocrystal\$6 and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 08:23
L7	1	L4 and monocrystal\$6 and chip and filter	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 08:23
L10	3	L4 and membrane and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 09:34
L11	14	L4 and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 09:56
L12	2	L4 and filter and wall	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 09:42
L13	2	L4 and filter and wall	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 09:43

L14	. 21	"5689087" and circuit and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR.	ON	2006/05/10 10:43
L15	6	"5689087" and filter	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 10:43
L16	17	("5059543"   "5100479"   "5470797"   "5515735"   "5689087"   "5883310"   "5914507"   "5982014"   "5994188"   "6109113"   "6127701"   "6294787"   "6369646"   "6472243"   "6525880"   "6631638").PN. OR ("6828172").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/10 10:54
L17	1	L16 and substrate and filter and chip	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/10 12:44
L18	21	(US-20020023765-\$).did. or (US-6031231-\$ or US-6316770-\$ or US-6891259-\$ or US-6238085-\$ or US-7022990-\$ or US-6686653-\$ or US-6603183-\$ or US-5369280-\$ or US-7038288-\$ or US-5689087-\$ or US-6222111-\$ or US-6163061-\$ or US-5374123-\$ or US-6949286-\$ or US-6229144-\$ or US-5804847-\$ or US-6335478-\$).did. or (US-6384473-\$ or US-6603183-\$). did.	US-PGPUB; USPAT; DERWENT	OR	ON	2006/05/10 11:19
L19	7	L18 and substrate and cavity and chips	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 11:23
L20	. 4	L18 and substrate and cavity and chips and germanium	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 11:30
L21	5	L18 and substrate and cavity and (chips or wafers) and germanium	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 11:30
L22	. 3	L18 and substrate and cavity and (chips or wafers) and germanium and stack	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 11:31

L23	3	L18 and substrate and cavity and (chips or wafers) and germanium and stack\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 11:42
L24	1	L18 and substrate and cavity and (chips or wafers) and germanium and stack\$4 and antireflect\$\$	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 11:43
L25	1	L18 and substrate and cavity and (chips or wafers) and germanium and stack\$4 and antireflect\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 11:43
L26	2	L18 and substrate and cavity and antireflect\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 11:43
L27	3	L18 and substrate and cavity and (anti adj reflect\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 11:43
L32	16	"250"\$.ccls. and ((substrate or wafer) and cavity and (stack\$4 same (substrates or chips)) and window and (anti adj reflect\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 12:43
L33	4	L16 and (stack\$4 same (substrates or chips))	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/10 12:51
L34		L16 and (stack\$4 same (substrates or chips)) and packages	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/10 12:51
L36	2	L4 and (anti adj reflect\$4) and window and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 13:34
L37	13	L4 and cap\$5 and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 13:40
L38	3	L4 and cap\$5 and substrate and lid	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 13:41
L39	1892	250/338.1.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:11

L40	489	250/338.4.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:11
L41	989	250/336.1.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:11
L42	836	250/332.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:11
L43	448	250/370.08.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:12
L46	764	257/448.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:12
L47	690	257/434.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:12
L50	795	257/687.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:12
L51	325	257/257.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:12
L52	35	L39 and substrate and cavity and thermopile and sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON .	2006/05/10 14:13
L53	16	L40 and substrate and cavity and thermopile and sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:13
L54	1	L41 and substrate and cavity and thermopile and sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:13
L56	13	L42 and substrate and cavity and thermopile and sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:14

L58	2	L47 and substrate and cavity and thermopile and sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:14
L61	6	L39 and monocrysta\$6 and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:14
L62	8	L40 and monocrysta\$6 and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:14
L64	5	L42 and monocrysta\$6 and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:14
L65	5	L43 and monocrysta\$6 and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:14
L66	4	L46 and monocrysta\$6 and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:14
L67	5	L47 and monocrysta\$6 and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:15
L68	11	L50 and monocrysta\$6 and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:15
L69	2	L51 and monocrysta\$6 and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:15
L70	23	("20040164981"   "4418284"   "5433911"   "5753857"   "5811799"   "5865935"   "6011294"   "6143588"   "6266197"   "6285064"   "6351027"   "6358773"   "6428650"   "6509560"   "6534340"   "6603183"   "6753203"   "6762492"   "6874227"   "6856014"   "6874227"   "6900531"   "6905910").PN. OR ("6995462").	US-PGPUB; USOCR	OR	ON	2006/05/10 14:15

L71	13	L70 and (substrate or wafer or chip) and (cavity or aperture) and sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:15
L72	169	L39 and (substrate or wafer or chip) and (cavity or aperture) and sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ΘN	2006/05/10 14:15
L73	98	L40 and (substrate or wafer or chip) and (cavity or aperture) and sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:15
L76	41	L41 and (substrate or wafer or chip) and (cavity or aperture) and sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:16
L77	131	L42 and (substrate or wafer or chip) and (cavity or aperture) and sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:16
L78	44	L43 and (substrate or wafer or chip) and (cavity or aperture) and sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:16
L79	51	L46 and (substrate or wafer or chip) and (cavity or aperture) and sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:16
L80	84	L47 and (substrate or wafer or chip) and (cavity or aperture) and sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:16
L81	34	L50 and (substrate or wafer or chip) and (cavity or aperture) and sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:16
L82	11	L51 and (substrate or wafer or chip) and (cavity or aperture) and sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:16
L83	1708	"257"\$.ccls. and integrat\$4 and substrate and window and filter\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:17
L84	15	L72 and integrat\$4 and substrate and window and filter\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:17

L85	16	L73 and integrat\$4 and substrate and window and filter\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:17
L86	3.	L76 and integrat\$4 and substrate and window and filter\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:17
L87	16	L77 and integrat\$4 and substrate and window and filter\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:17
L88	3	L78 and integrat\$4 and substrate and window and filter\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:17
L89	2	L79 and integrat\$4 and substrate and window and filter\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:17
L90	17	L80 and integrat\$4 and substrate and window and filter\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:17
L91	1	L81 and integrat\$4 and substrate and window and filter\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:17
<b>S1</b>	1891	250/338.1.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 08:06
S2	35	S1 and substrate and cavity and thermopile and sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:13
S3	48	"6384473"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/05 10:40
S4	9	"6603183"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/05 10:40
S5	4	"6686653"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/05 10:40

S6	2	"20020023765"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/05 10:40
<b>S7</b>	4	(US-20020023765-\$).did. or (US-6686653-\$).did. or (US-6384473-\$ or US-6603183-\$). did.	US-PGPUB; USPAT; DERWENT	OR	ON	2006/05/05 10:40
<b>S8</b>	1	S7 and substrate and cavity and thermopile and sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 16:20
. S9	18	("4701424"   "5196919"   "5397897"   "5420419"   "5459351"   "5521123"   "5528452"   "5585311"   "5729019"   "5895233"   "6062461"   "6066808"   "6396116"   "6483030").PN. OR ("6686653").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/05 10:41
S10	. 12	("20030146384"   "4008945"   "5498900"   "5798557"   "5818094"   "5932875"   "6062461"   "6074891"   "6147389"   "6670538"   "6686653"   "6846690").PN. OR ("7022990").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/05 10:42
S11	3	S10 and substrate and cavity and thermopile and sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/05 10:44
S12	21	("4926227"   "5122561"   "5359208"   "5867368").PN. OR ("6147389").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/05 10:43
S13	10	S12 and substrate and cavity and sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/05 10:45
S14	5	S10 and substrate and cavity and sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR .	ON	2006/05/05 10:46
S15	11	S9 and substrate and cavity and sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/05 10:46

S16	1	S7 and substrate and cavity and sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/05 10:48
S17	6	("20020023765"   "5895233"   "6384473"   "6603183"   "6686653").PN. OR ("6844606"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/05 10:47
S18	2	S17 and substrate and cavity and sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/05 10:48
S19	55	S1 and substrate and cavity and thermo\$4 and sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/05 11:00
S20	9	S1 and substrate and cavity and thermo\$4 and sensor and support and membrane	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/05 11:01
S21	7	S1 and substrate and cavity and thermo\$4 and sensor and support and membrane and window	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/05 11:01
S22	52	"250"\$.ccls. and ((substrate or wafer) and cavity and membrane and optical and wavelength and micrometer)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 12:41
S23	3	S1 and ((substrate or wafer) and cavity and membrane and optical and wavelength and micrometer)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/05 11:18
S24	22	("4158133"   "4902136"   "5144498"   "5216237"   "5321539"   "5365770").PN. OR ("5589689").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/05 11:21
S25	147454	thermopile and (substrate or wafer) and cavity and wavelength an micrometers	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/05 11:25
S26	39	thermopile and (substrate or wafer) and cavity and wavelength and micrometers	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/05 11:32
S27	26	thermopile and (substrate or wafer) and cavity and wavelength and micrometers and wall	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/05 11:32

S28 ·	24	S1 and substrate and cavity and thermopile and sensor and wall	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/05 11:33
S29	9	"6603183"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/05 11:42
S30	12	("5122861"   "5615052"   "5753857"   "5865935"   "6117705"   "6144107"   "6185180").PN. OR ("6603183"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/05 11:42
S31	18	("20020185748"   "20030183909"   "4801998"   "5518660"   "5796582"   "5909056"   "6278182"   "6282096"   "6317326"   "6369380"   "6392890"   "6407461"   "6549407"   "6603183"   "6654248").PN. OR ("6891259"). URPN.	US-PGPUB; USPAT; USOCR	OR:	ΘN	2006/05/05 11:43
S32	335159	"257"\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/05 11:44
S33	61	S32 and substrate and cavity and thermopile and sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/05 12:08
S34	20	("5288649"   "5523564"   "5534111"   "5560711"   "5583058"   "5594248"   "5850098").PN. OR ("6163061"). URPN.	US-PGPUB; USPAT; USOCR	OR -	ON	2006/05/05 12:06
S35	8	S34 and substrate and cavity and thermopile and sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/05 12:18
S36 ·		S34 and (substrate or wafer or chip) and cavity and thermopile and sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/05 12:44
S37	8	("20020009821"   "6048092"   "6163061"   "6222454"   "6335478"   "6548879"   "6603160"   "6608356").PN. OR ("6806470").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/05 12:22

S38	23	("20040164981"   "4418284"   "5433911"   "5753857"   "5811799"   "5865935"   "6011294"   "6143588"   "6266197"   "6285064"   "6351027"   "6358773"   "6428650"   "6509560"   "6534340"   "6603183"   "6753203"   "6762492"   "6822326"   "6856014"   "6874227"   "6900531"   "6905910").PN. OR ("6995462"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/05 12:43
S39	0	S38 and (substrate or wafer or chip) and cavity and thermopile and sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/05 12:45
S40	13	S38 and (substrate or wafer or chip) and cavity and sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:15
S41	9	("5070041"   "6130448"   "6191359"   "6291263"   "6509636"   "6680525"   "6747261"   "6753922").PN. OR ("6874227").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/05 12:53
S42	23	("20040164981"   "4418284"   "5433911"   "5753857"   "5811799"   "5865935"   "6011294"   "6143588"   "6266197"   "6285064"   "6351027"   "6358773"   "6428650"   "6509560"   "6534340"   "6603183"   "6753203"   "6762492"   "6822326"   "6856014"   "6874227"   "6900531"   "6905910").PN. OR ("6995462"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/05 13:00
S43	1	S7 and substrate and cavity and sensor and wall	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/05 13:29

S44	18	("4701424"   "5196919"   "5397897"   "5420419"   "5459351"   "5521123"   "5528452"   "5585311"   "5729019"   "5895233"   "5914488"   "6036872"   "6062461"   "6066808"   "6396116"   "6483030").PN. OR ("6686653").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/05 13:29
S45	87	"250"\$.ccls. and substrate and cavity and membrane and sensor and reflect\$4 and ((wall or window) and silicon)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/05 14:08
S46	11	S45 and thermopile	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/05 13:55
S47	11	"250"\$.ccls. and substrate and cavity and membrane and sensor and reflect\$4 and ((wall or window) and silicon) and thermopile	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/05 14:11
S48	7	"257"\$.ccls. and substrate and cavity and membrane and sensor and reflect\$4 and ((wall or window) and silicon) and thermopile	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/05 14:11
S49	10	(US-20020023765-\$).did. or (US-6316770-\$ or US-6603183-\$ or US-6891259-\$ or US-6686653-\$ or US-7022990-\$ or US-5374123-\$ or US-6335478-\$).did. or (US-6384473-\$ or US-6603183-\$). did.	US-PGPUB; USPAT; DERWENT	OR	ON	2006/05/08 10:37
S50		("20020185748"   "20030183909"   "4801998"   "5518660"   "5796582"   "5909056"   "6278182"   "6282096"   "6317326"   "6369380"   "6392890"   "6407461"   "6515360"   "6535388"   "6549407"   "6603183"   "6654248").PN. OR ("6891259"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/08 08:04
S51	0	S49 and cacity and substrate and circuit and sens\$4 and window	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/08 09:36
S52	0	S49 and cacity and substrate and circuit and sens\$4	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/08 08:05

S53	3	S49 and cavity and substrate and circuit and sens\$4	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/08 08:44
S54	19	"5589689"	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/08 08:46
S55	9	"5589689" and cavity and substrate	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/08 08:48
S56	22	("4158133"   "4902136"   "5144498"   "5216237"   "5321539"   "5365770").PN. OR ("5589689").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/08 08:48
S57	9	S56 and cavity and substrate	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/08 08:49
S58	1489	cavity and substrate and (thermopile or thermocouple) and circuit and silicon	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/08 08:50
S59	468	cavity and substrate and (thermopile or thermocouple) and circuit and silicon and package	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/08 08:50
S60	102	"250"\$.ccls. and S58	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 11:46
S61	58	S60 and wall	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 09:01
S62	286	"257"\$.ccls. and S58	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 09:21
S63	180	S62 and wall	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 09:01
S64	20	("5288649"   "5523564"   "5534111"   "5560711"   "5583058"   "5594248"   "5850098").PN. OR ("6163061"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/08 09:21
S65	149	((infrared adj sensor) same package)	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/08 09:21

S66	28	"257"\$.ccls. and S65	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 09:30
S67	53	"250"\$.ccls. and S65	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 09:22
S68		"257"\$.ccls. and S65 and membrane and window	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 09:30
S69	17	("5059543"   "5100479"   "5470797"   "5515735"   "5689087"   "5883310"   "5914507"   "5982014"   "5994188"   "6127701"   "6294787"   "6369646"   "6472243"   "6525880"   "6631638").PN. OR ("6828172").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/08 09:30
S70		("3293082"   "3436274"   "3758830"   "3761318"   "4211888"   "4456919"   "4558342"   "4571608"   "5156688"   "5462608").PN. OR ("5689087").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/08 09:32
S72	50	"250"\$.ccls. and cavity and (substrate or wafer) and circuit and sens\$4 and window and (antiad) reflect\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 09:37
S73	50	"250"\$.ccls. and cavity and (substrate or wafer) and circuit and sens\$4 and window and (antiad) reflect\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 09:38
S74	67	"257"\$.ccls. and cavity and (substrate or wafer) and circuit and sens\$4 and window and (antiad) reflect\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 10:04
S75	53	("3069644"   "3675018"   "4110616"   "4116063"   "5021663"   "5118944"   "5293041").PN. OR ("5369280"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/08 09:40
S76	15	"257"\$.ccls. and cavity and (substrate or wafer) and circuit and sens\$4 and (anti adj reflect\$4) and (back same side) and illuminat\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ΘN	2006/05/08 10:05

S77	16	"250"\$.ccls. and cavity and (substrate or wafer) and circuit and sens\$4 and (anti adj reflect\$4) and (back same side) and illuminat\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 10:08
S78	110	"250"\$.ccls. and cavity and (substrate or wafer) and circuit and sens\$4 and (back same side) and illuminat\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 10:17
S79	188	"257"\$.ccls. and cavity and (substrate or wafer) and circuit and sens\$4 and (back same side) and illuminat\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 10:12
S80	37	S78 and package	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 10:09
S81	114	S79 and package	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 10:09
S82	35	"600"\$.ccls. and cavity and (substrate or wafer) and circuit and sens\$4 and (back adj side) and illuminat\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 10:13
S83	485	"250"\$.ccls. and (cavity or hole or etch\$4) and (substrate or wafer) and circuit and sens\$4 and (back same side) and illuminat\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 10:17
S84	566	"257"\$.ccls. and (cavity or hole or etch\$4) and (substrate or wafer) and circuit and sens\$4 and (back same side) and illuminat\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 10:17
S85	360	"257"\$.ccls. and (cavity or hole) and etch\$4 and (substrate or wafer) and circuit and sens\$4 and (back same side) and illuminat\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 10:54
S86	175	"250"\$.ccls. and (cavity or hole) and etch\$4 and (substrate or wafer) and circuit and sens\$4 and (back same side) and illuminat\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 11:07
S87	78	S85 and membrane	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 10:36
S88		S86 and membrane	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 10:18

S89	1	S49 and (back same side)	US-PGPUB; USPAT; DERWENT	OR	ON	2006/05/08 10:38
S90	18	("20020185748"   "20030183909"   "4801998"   "5518660"   "5796582"   "5909056"   "6278182"   "6282096"   "6317326"   "6369380"   "6515360"   "6549407"   "6603183"   "6654248").PN. OR ("6891259"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/08 10:37
S91	3	S90 and (back same side)	US-PGPUB; USPAT; DERWENT	OR	ON	2006/05/08 10:38
S92	15	("20030089958"   "20050051859"   "4491983"   "5049521"   "5973337"   "6143588"   "6348682"   "6483101"   "6521476"   "6586721"   "6614103"   "6633421"   "6686580"   "6737720").PN. OR ("7038288"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/08 10:41
S93	5	250/338\$.ccls. and (cavity or hole) and etch\$4 and (substrate or wafer) and circuit and sens\$4 and (back same side) and illuminat\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/09 14:44
S94	8	250/338\$.ccls. and (cavity or hole) and (substrate or wafer) and circuit and sens\$4 and (back same side) and illuminat\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 11:04
S95	0	220/338\$.ccls. and (cavity or hole) and (substrate or wafer) and circuit and sens\$4 and (back same side) and illuminat\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 10:56
S96	30	thermopile and (cavity or hole) and (substrate or wafer) and circuit and sens\$4 and (back same side) and illuminat\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 11:06
S97	27	thermopile and (cavity or hole) and (substrate or wafer) and circuit and sens\$4 and (back same side) and illuminat\$5 and window	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 11:04
S98	241	(thermopile or thermocouple) and (cavity or hole) and (substrate or wafer) and circuit and sens\$4 and (back same side) and illuminat\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 11:25

S99	13	"250"\$.ccls. and S98	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 11:13
S10 0	36	"257"\$.ccls. and S98	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 11:07
S10 1	249	"250"\$.ccls. and thermopile and window	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 16:49
S10 2	86	(substrate or wafer) and circuit and S101	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 11:13
S10 3	10	(thermopile or thermocouple) and (cavity or hole) and (substrate or wafer) and circuit and sens\$4 and ((back adj side) same illuminat\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 11:28
S10 4	5389	(thermopile or thermocouple) and (cavity or hole) and (substrate or wafer) and circuit	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 11:28
S10 5	233	(thermopile or thermocouple) and (cavity or hole) and (substrate or wafer) and circuit and (window same pass)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 11:36
S10 6	17	(thermopile or thermocouple) and (cavity or hole) and (substrate or wafer) and circuit and (window same pass) and (back same illuminat\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 11:37
S10 7	336	sens\$4 and (cavity or hole) and (substrate or wafer) and circuit and (window same pass) and (back same illuminat\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 11:37
S10 8	48	S107 and thermo\$7	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 11:38
S10 9	18	("4883561"   "5357122"   "5625726"   "5773331"   "5821138"   "5916585"   "5953597"   "5976953"   "5985742"   "5994207"   "6010579"   "6013563"   "6127199"   "6143582").PN. OR ("6627518").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/08 11:43

S11 0	127	"250"\$.ccls. and substrate and cavity and (back same illuminat\$5) and circuit	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 11:50
S11 3	3	"6455858"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 12:29
S11 4	107	257/460.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 16:20
S11 5	160	257/447.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 16:19
S11 6	0	S114 and substrate and cavity and thermopile and sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 16:19
S11 7	1	S115 and substrate and cavity and thermopile and sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 16:19
S11 8	61	"257"\$.ccls. and substrate and cavity and thermopile and sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 16:36
S11	22	("4894698"   "5659195"   "5852320"   "5894144"   "5929497"   "6066882"   "6150681"   "6169316"   "6201285"   "6229190"   "6378167"   "6319743"   "6369931"   "6357299"   "63883832"   "6388279"   "6388299"   "6405594").PN. OR ("6551853").URPN.	US-PGPUB; USOCR	OR	ON	2006/05/08 16:21
S12 0	22	("4894698"   "5659195"   "5852320"   "5894144"   "5929497"   "6066882"   "6150681"   "6169316"   "6201285"   "6229190"   "6278167"   "6319743"   "6326682"   "6357299"   "6369931"   "6376889"   "63883832"   "6388279"   "6388299"   "6405594").PN. OR ("6551853").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/08 16:24

S12 2	9	S120 and substrate and cavity and sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 16:26
S12 3	45	"257"\$.ccls. and substrate and cavity and thermopile and sensor and (silicon same infrared)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 16:39
S12 4	3	"257"\$.ccls. and substrate and cavity and thermopile and sensor and (silicon same infrared) and (back same irradiat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 16:44
S12 5	3	"250"\$.ccls. and substrate and cavity and thermopile and sensor and (silicon same infrared) and (back same irradiat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 16:45
S12 6	2	"250"\$.ccls. and substrate and cavity and thermopile and sensor and ((silicon or base) same (pass same (radiation or infrared))) and (back same irradiat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR .	ON	2006/05/08 16:46
S12 7	33	"250"\$.ccls. and sens\$4 and (cavity or hole) and (substrate or wafer) and circuit and (window same pass) and (back same illuminat\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 16:55
S12 8	118	"250"\$.ccls. and sens\$4 and (cavity or hole) and (substrate or wafer) and circuit and filter and etch\$4 and (back same illuminat\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 16:55
S12 9	96	"250"\$.ccls. and sens\$4 and (cavity or hole) and (substrate or wafer) and circuit and filter and etch\$4 and (back same illuminat\$5) and silicon	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 16:56
S13 0	· . 51	"250"\$.ccls. and sens\$4 and (cavity or hole) and (substrate or wafer) and circuit and filter and etch\$4 and (back same illuminat\$5) and silicon and (reflect\$4 same layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 16:58
S13	3	"250"\$.ccls. and sens\$4 and (cavity or hole) and (substrate or wafer) and circuit and filter and etch\$4 and (back same illuminat\$5) and silicon and (reflect\$4 same layer) and membrane	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 16:56

S13 2		"250"\$.ccls. and sens\$4 and (cavity or hole) and (substrate same back) and circuit and filter and etch\$4 and (back same illuminat\$5) and silicon and (reflect\$4 same layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 16:59
S13	63	"257"\$.ccls. and sens\$4 and (cavity or hole) and (substrate same back) and circuit and filter and etch\$4 and (back same illuminat\$5) and silicon and (reflect\$4 same layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON .	2006/05/08 17:03
S13 4	42	"257"\$.ccls. and sens\$4 and (cavity or hole) and (substrate same back) and circuit and filter and etch\$4 and (back same illuminat\$5) and silicon and (reflect\$4 same layer) and stack	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/08 17:03
<b>5</b> 13	18	(US-20020023765-\$).did. or (US-6891259-\$ or US-6603183-\$ or US-7022990-\$ or US-6686653-\$ or US-6335478-\$ or US-6316770-\$ or US-6163061-\$ or US-5374123-\$ or US-5689087-\$ or US-6238085-\$ or US-6229144-\$ or US-5369280-\$ or US-5804847-\$ or US-7038288-\$ or US-6627518-\$).did. or (US-6384473-\$ or US-6603183-\$). did.	US-PGPUB; USPAT; DERWENT	OR	ON	2006/05/09 14:06
S13 6	1892	250/338.1.ccis.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/09 14:37
S13 7	18	S136 and integrat\$4 and thermopile and substrate and cavity	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/09 14:09
S13 8	6	S136 and integrat\$4 and thermopile and substrate and cavity and window	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/09 14:34
S13 9	6	S136 and integrat\$4 and thermopile and substrate and cavity and window and infrared	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/09 14:37
S14 0		250/338\$.ccls. and integrat\$4 and thermopile and substrate and cavity and window and infrared and wall	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR ·	ON	2006/05/09 14:58

C14	, ,	1125011t colo and integrated and	LIC DCDLID	On	ON	2006/0E/00 14:40
S14 1	1	"250"\$.ccls. and integrat\$4 and thermopile and substrate and cavity and window and infrared and wall and (back same irradiat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/09 14:40
S14 3	15	"257"\$.ccls. and integrat\$4 and thermopile and substrate and cavity and window and infrared and wall	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/09 14:41
S14 4	3	"257"\$.ccls. and integrat\$4 and thermopile and substrate and cavity and window and infrared and wall and back and filter\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:17
S14 5	6	"250"\$.ccls. and integrat\$4 and thermopile and substrate and cavity and window and infrared and wall and back and filter\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/09 14:42
S14 6	<b>17</b>	("5059543"   "5100479"   "5470797"   "5515735"   "5689087"   "5883310"   "5914507"   "5982014"   "5994188"   "6109113"   "6127701"   "6294787"   "6369646"   "6472243"   "6525880"   "6631638").PN. OR ("6828172").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/09 14:42
S15 2	2	250/330\$.ccls. and (cavity or hole) and etch\$4 and (substrate or wafer) and circuit and sens\$4 and (back same side) and illuminat\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/10 14:11
S15 3	1	250/338\$.ccls. and integrat\$4 and thermopile and substrate and cavity and window and infrared and wall and bandgap	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/09 14:59
S15 4	5	250/338\$.ccls. and integrat\$4 and thermopile and substrate and cavity and window and infrared and wall and absorb\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/09 14:59
S15 5	8	250/338\$.ccls. and integrat\$4 and thermopile and substrate and cavity and window and infrared and absorb\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/09 14:59

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S15 6	48	("3147436"   "3293082"   "3354309"   "3405271"   "3405272"   "3405273"   "3424624"   "3611805"   "3687713"   "3715288"   "3781549"   "3965568"   "4098617"   "4148052"   "4229066"   "4282290"   "4293768"   "4436363"   "4456919"   "4459484"   "4558342"   "4956555"   "5038041"   "5041723"   "5056929"   "5072109"   "5099121"   "5100479"   "5138164"   "5157258"   "5159199"   "5300778"   "5393351").PN. OR ("6222111"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/09 15:03
S15 7	17	("20020018887"   "20020025425"   "3405271"   "4111717"   "4282290"   "5316854"   "5412279"   "5545897"   "5689087"   "5982014"   "6060151"   "6222111"   "6368400").PN. OR ("6949286"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/09 15:04
S15 8		("3147436"   "3293082"   "3354309"   "3405271"   "3405272"   "3405273"   "3424624"   "3611805"   "3687713"   "3715288"   "3781549"   "3965568"   "4098617"   "4148052"   "4229066"   "4282290"   "4293768"   "4436363"   "4456919"   "4459484"   "4558342"   "4956555"   "5038041"   "5041723"   "5056929"   "5072109"   "5099121"   "5100479"   "5138164"   "5157258"   "5159199"   "5300778"   "5393351").PN. OR ("6222111"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/09 15:18

S15 9	21	(US-20020023765-\$).did. or (US-6891259-\$ or US-6603183-\$ or US-7022990-\$ or US-6686653-\$ or US-6335478-\$ or US-6316770-\$ or US-6163061-\$ or US-5374123-\$ or US-5689087-\$ or US-6238085-\$ or US-6229144-\$ or US-5369280-\$ or US-5804847-\$ or US-7038288-\$ or US-6627518-\$ or US-6031231-\$ or US-6949286-\$).did. or (US-6384473-\$ or US-6603183-\$).	US-PGPUB; USPAT; DERWENT	OR	ON	2006/05/09 15:45
S16 0	5	S159 and membrane	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/09 16:38
S16 1	14	S159 and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/09 16:38